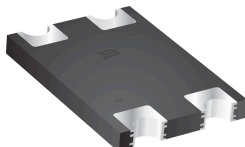


MATERIAL DECLARATION SHEET



Material Number	CD-MBL1xxS CD-MBL1xxSL			
Product Line	Semiconductor Products			
Compliance Date	2006/06/26			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	42.5	Continuous filament glass fibers	65997-17-3	43	26.107	60.714
				Copper	7440-50-8	14	8.5	
				Non-Hazardous cured resin	Proprietary	43	26.107	
2	Epoxy	Plastic	20.3	Silicon Dioxide	7631-86-9	55	15.95	29
				Epoxy resin	9003-36-5	45	13.05	
3	Solder Cream	Metal	1.523	Lead ²	7439-92-1	88	1.91488	2.176
				Tin	7440-31-5	10	0.2176	
				Silver	7440-22-4	2	0.04352	
4	Dice	Others	4.277	Silicon	7440-21-3	35.77	2.186	6.11
				Nickel	7440-02-0	0.7	0.043	
				Lead-containing glass ³	7439-92-1	63.51	3.88	
				Gold	7440-57-5	0.02	0.001	
5	Terminal Plating	Metal	1.4	Tin	7440-31-5	100	2	2
			Total weight	70				

This Document was updated on: 2016/4/7

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.

MATERIAL DECLARATION SHEET

BOURNS®

2. **Excepted for RoHS 7(a) (Lead in high temp solder)**
3. **Excepted for RoHS 7(c) I (Lead in a glass)**